

c1 the capacitor comprises:

a pair of electrodes or electrode groups; and

the capacitor comprises a plurality of capacitor terminals projecting beyond the planar surface of the printed wiring substrate, wherein the respective capacitor terminals are electrically connected to one or the other of the paired electrodes or electrode groups;

Cont'd the printed wiring substrate comprises a plurality of substrate terminals;

B1 the IC chip comprises a plurality of connection-to-capacitor terminals and a plurality of connection-to-substrate terminals;

the plurality of capacitor terminals of the capacitor are respectively flip-chip-bonded directly to a plurality of connection-to-capacitor terminals of the IC chip; and

the plurality of substrate terminals of the printed wiring substrate are respectively flip-chip-bonded to a plurality of connection-to-substrate terminals of the IC chip.

2. (Twice Amended) A printed wiring substrate having a planar surface and a built-in capacitor distinct from the printed wiring substrate on which an IC-chip-carrying printed wiring substrate is mounted, said printed wiring substrate comprising a capacitor accommodation cavity for accommodating the capacitor, characterized in that:

the capacitor comprises:

a pair of electrodes or electrode groups; and

C1 the capacitor comprises a plurality of capacitor terminals projecting beyond the planar surface of the printed wiring substrate, wherein the respective capacitor terminals are electrically connected to one or the other of the paired electrodes or electrode groups;

the printed wiring substrate comprises a plurality of substrate terminals;

the IC chip-carrying printed wiring circuit comprises a plurality of connection-to-capacitor terminals and a plurality of connection-to-substrate terminals;

the plurality of capacitor terminals of the capacitor are respectively bonded in a connection-face-to-connection-face manner directly to a plurality of connection-to-capacitor terminals of the IC-chip-carrying printed wiring substrate; and

the plurality of substrate terminals of the printed wiring substrate are respectively bonded in a connection-face-to-connection-face manner to a plurality of connection-to-substrate terminals of the IC-chip-carrying printed wiring substrate.

Sub C2 4. (Twice Amended) A printed wiring substrate having a planar surface and a built-in capacitor distinct from the printed wiring substrate for mounting an IC chip or IC-chip-carrying printed wiring substrate having a plurality of connection-to-capacitor terminals and a plurality of connection-to-substrate terminals, said printed wiring substrate comprising a capacitor accommodation cavity for accommodating the capacitor, characterized in that:

the capacitor comprises:

a pair of electrodes or electrode groups; and

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the capacitor comprises a plurality of capacitor terminals projecting beyond the planar surface of the printed wiring substrate capable of being respectively flip-chip-bonded or bonded in a connection-face-to-connection-face manner to a plurality of connection-to-capacitor terminals of the IC chip or IC-chip-carrying printed wiring substrate, wherein the respective capacitor terminals are electrically connected to one or the other of the paired electrodes or electrode groups; and

the printed wiring substrate comprises a plurality of substrate terminals capable of being respectively flip-chip-bonded or bonded in a connection-face-to-connection-face manner directly to a plurality of connection-to-substrate terminals of the IC chip or IC-chip-carrying printed wiring substrate.